

SKiiP 942 GB 120 - 317 CTV

Absolute Maximum Ratings		Values	Units
Symbol	Conditions ¹⁾		
$V_{\text{isol}}^{(4)}$	AC, 1min	3000	V
$T_{\text{op}}, T_{\text{stg}}$	Operating / stor. temperature	-25...+85	°C
IGBT and Inverse Diode			
V_{CES}		1200	V
$V_{\text{CC}}^{(5)}$	Operating DC link voltage	900	V
I_{C}	IGBT	900	A
$T_j^{(3)}$	IGBT + Diode	-40...+150	°C
I_F	Diode	900	A
I_{FM}	Diode, $t_p < 1 \text{ ms}$	1800	A
I_{FSM}	Diode, $T_j = 150 \text{ °C}, 10\text{ms}; \sin$	6480	A
I^2t (Diode)	Diode, $T_j = 150 \text{ °C}, 10\text{ms}$	210	kAs ²
Driver			
V_{S1}	Stabilized Power Supply	18	V
V_{S2}	Non-stabilized Power Supply	30	V
f_{smax}	Switching frequency	20	kHz
dV/dt	Primary to secondary side	75	kV/μs

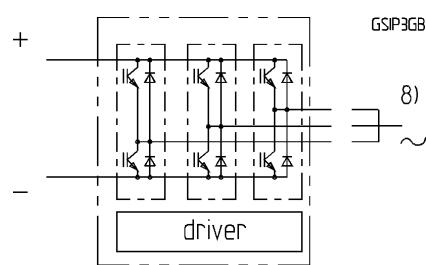
Characteristics		min.	typ.	max.	Units
Symbol	Conditions ¹⁾				
IGBT ⁽¹¹⁾					
$V_{(\text{BR})\text{CES}}$	Driver without supply	$\geq V_{\text{CES}}$	—	—	V
I_{CES}	$V_{\text{GE}} = 0, T_j = 25 \text{ °C}$	—	—	1,2	mA
	$V_{\text{CE}} = V_{\text{CES}}, T_j = 125 \text{ °C}$	—	45	—	mA
V_{TO}	$T_j = 125 \text{ °C}$	—	—	1,38	V
r_T	$T_j = 125 \text{ °C}$	—	—	2,5	mΩ
V_{Cesat}	$I_{\text{C}} = 750\text{A}, T_j = 125 \text{ °C}$	—	—	3,2	V
V_{Cesat}	$I_{\text{C}} = 750\text{A}, T_j = 25 \text{ °C}$	—	—	3,05	V
$E_{\text{on}} + E_{\text{off}}$	$V_{\text{CC}}=600/900\text{V}, I_{\text{C}}=900\text{A}$ $T_j = 125 \text{ °C}$	—	—	270/439	mJ
C_{CHC}	per Phase, AC side	—	4,2	—	nF
L_{CE}	Top, Bottom	—	5	—	nH
Inverse Diode ²⁾					
$V_F = V_{\text{EC}}$	$I_F = 750\text{A}; T_j = 125 \text{ °C}$	—	—	2,43	V
$V_F = V_{\text{EC}}$	$I_F = 750\text{A}; T_j = 25 \text{ °C}$	—	—	2,55	V
$E_{\text{on}} + E_{\text{off}}$	$I_F = 900\text{A}; T_j = 125 \text{ °C}$	—	—	36	mJ
V_{TO}	$T_j = 125 \text{ °C}$	—	—	0,91	V
r_T	$T_j = 125 \text{ °C}$	—	—	1,3	mΩ
Thermal Characteristics					
$R_{\text{thjs}}^{(10)}$	per IGBT	—	—	0,030	K/W
$R_{\text{thjs}}^{(10)}$	per Diode	—	—	0,083	K/W
$R_{\text{thsa}}^{(6,10)}$	P16 heatsink; see case S3	—	—	36	K/KW
Driver					
I_{S1}	Supply current 15V-supply	$260+320*f_s/f_{\text{smax}}+1,3*I_{\text{AC}}/A$		mA	
I_{S2}	Supply current 24V-supply	$200+210*f_s/f_{\text{smax}}+1,0*I_{\text{AC}}/A$		mA	
$t_{\text{interlock-driver}}$	Interlock-time	2,3		μs	
SKiiPPACK protection					
I_{TRIPSC}	Short circuit protection	1125		A	
I_{TRIPLG}	Ground fault protection	-		A	
T_{TRIP}	Over-temp. protection	115		°C	
$U_{\text{DCTRIP}}^{(9)}$	U_{DC} -protection	920		V	
Mechanical Data					
M1	DC terminals, SI Units	4	—	6	Nm
M2	AC terminals, SI Units	8	—	10	Nm

SKiiPPACK®

SK integrated intelligent
Power PACK
halfbridge
SKiiP

942 GB 120 - 317 CTV ^{7,9)}

Preliminary Data
Case S3



Features

- Short circuit protection, due to evaluation of current sensor signals
- Isolated power supply
- Low thermal impedance
- Optimal thermal management with integrated heatsink
- Pressure contact technology with increased power cycling capability, compact design
- Low stray inductance
- High power, small losses
- Over-temperature protection

¹⁾ $T_{\text{heatsink}} = 25 \text{ °C}$, unless otherwise specified

²⁾ CAL = Controlled Axial Lifetime Technology (soft and fast)

³⁾ without driver

⁴⁾ Driver input to DC link / AC output to DC link / AC output to heatsink

⁵⁾ with Semikron-DC link (low inductance)

⁶⁾ other heatsinks on request

⁷⁾ C - Integrated current sensors
T - Temperature protection

⁸⁾ V - 15 V or 24 V power supply
AC connection busbars must be connected by the user; copper busbars available on request

⁹⁾ options available for driver:
U - DC link voltage sense

F - Fiber optic connector

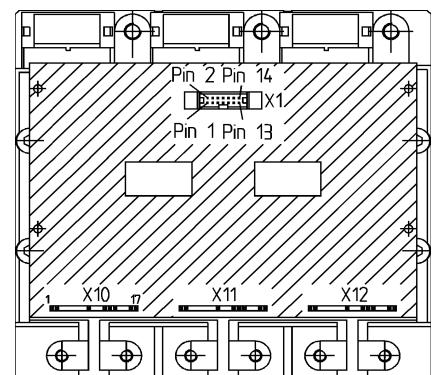
¹⁰⁾ "s" referenced to temperature sensor

¹¹⁾ NPT-technology with homogenous current-distribution

PIN-array - halfbridge driver SKiiPPACK 3-fold type "GB"

X1:

Pin	signal	remark
1	shield	connected to GND, when shielded cable is used
2	BOT IN ⁴⁾	positive 15V CMOS logic; 10 kΩ impedance, don't connect when using fiber optic
3	ERROR OUT ¹⁾	LOW = NO ERROR; open Collector Output; max. 30 V / 15 mA don't connect when using fiber optic, propagation delay 1 µs min. pulselwidth error-memory-reset 8 µs
4	TOP IN ⁴⁾	positive 15V CMOS logic; 10 kΩ impedance don't connect when using fiber optic
5	Overtemp. OUT ¹⁾	LOW = NO ERROR = $\vartheta_{DCB} < 115 \pm 5^\circ\text{C}$ open collector Output; max. 30 V / 15 mA .low" output voltage < 0,6 V .high" output voltage max. 30 V
6	+ 24 V _{DC} IN	24 V _{DC} (20 - 30 V)
7	+ 24 V _{DC} IN	don't supply with 24 V, when using + 15 V _{DCIN} supply voltage monitoring threshold 19,5 V
8	+ 15 V _{DC} IN	15 V _{DC} ± 4 %
9	+ 15 V _{DC} IN	don't supply with 15 V, when using + 24 V _{DCIN} supply voltage monitoring threshold 13 V
10	GND	GND for power supply and
11	GND	GND for digital signals
12	Temp. analog OUT or U _{DC} analog OUT ²⁾	U _{DC} when using option "U" actual DC-link voltage, 9 V refer to U _{DCmax} max. output current 5 mA; overvoltage trip level 9 V
13	GND aux ³⁾	GND for analog signals
14	I analog OUT	current actual value; 8,0 V refer to I _C @ 25 °C overcurrent trip level 10 V ⇔ 125 % I _C @ 25 °C current value > 0 ⇔ SKiiP is source current value < 0 ⇔ SKiiP is sink



X10: halfbridge 1 (HB1) OUT

Pin	Signal
1	
2	
8	Collector TOP (HB1)
11	Gate TOP (HB1)
12	Emitter TOP (HB1)
13	Collector BOT (HB1)
16	Gate BOT (HB1)
17	Emitter BOT (HB1)

type "GAL"

as type "GB" except

- PIN X1-4: connect this pin to GND
- TOP switch does not exist

X11: halfbridge 2 (HB2) OUT

Pin	Signal
1	Temp.-Sensor (HB2)1
2	Temp.-Sensor (HB2)2
8	Collector TOP (HB2)
11	Gate TOP (HB2)
12	Emitter TOP (HB2)
13	Collector BOT (HB2)
16	Gate BOT (HB2)
17	Emitter BOT (HB2)

type "GAR"

as type "GB" except

- PIN X1-2: connect this pin to GND
- BOTTOM switch does not exist

X12: halfbridge 3 (HB3) OUT

Pin	Signal
1	
2	
8	Collector TOP (HB3)
11	Gate TOP (HB3)
12	Emitter TOP (HB3)
13	Collector BOT (HB3)
16	Gate BOT (HB3)
17	Emitter BOT (HB3)

¹⁾ Open collector output, external pull up resistor necessary

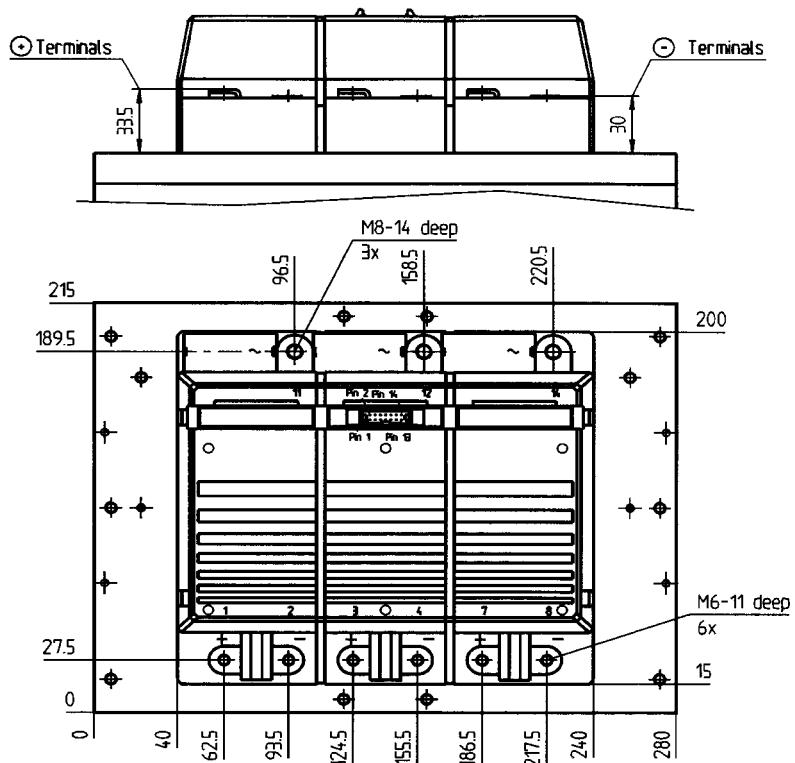
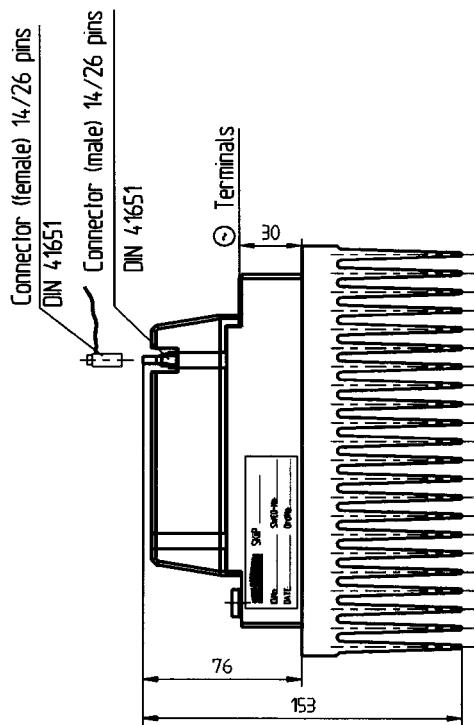
²⁾ When using option "U" the analog temperature signal is not available

³⁾ GND aux = reference for analog output signals

⁴⁾ „high“ (min) 11,2 V
„low“ (max) 5,4 V

Case S3

SKiiPPACK 3 - GB; GD



Weight without heatsink: 2,72 kg
P16:
6,6 kg

SKiiPPACK 3 - GB with F-option

